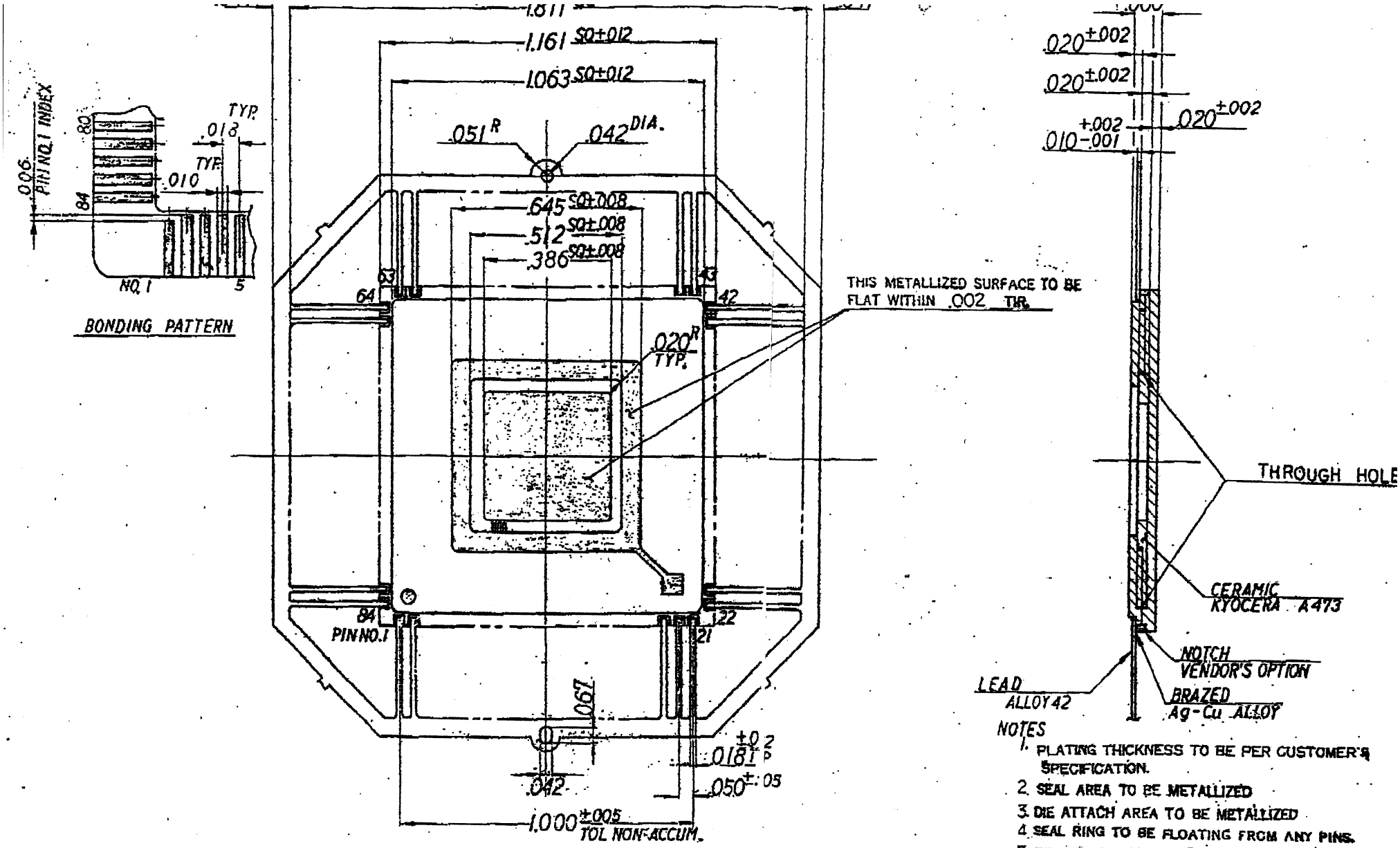

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED
3. DIE ATTACH AREA TO BE METALLIZED
4. SEAL RING TO BE FLOATING FROM ANY PINS.
5. DIE ATTACH PAD TO BE FLOATING FROM ANY PINS

CHANGE	DATE	DRAWN	CHECKED	APPROVED

84 LEAD FLAT PACKAGE

SCALE	MATERIAL
1	AS INDICATED

TOLERANCES: UNLESS OTHERWISE SPECIFIED ±.005

DRAWN	CH
K. Kamiyoshi	
APPROVED	
T. Aoki	JUL

FW084U447-1

KYOCERA CORPORATION

SSM P/N CCF08407